



DETERMINATION OF ELECTRICAL AND THERMAL PARAMETERS OF VERTICAL-CAVITY SURFACE-EMITTING LASERS

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Abstract

Experimental methods are presented for determining the thermal resistance of vertical-cavity surface-emitting lasers (VCSELs) and the lateral electrical conductivity of their p-type semiconductor layers. A VCSEL structure was manufactured from III-As compounds on a gallium arsenide substrate. Conductivity was determined using transmission line measurement (TLM). Electrical and thermal parameters were determined for various ambient temperatures. The results could be used for computer analysis of VCSELs.

Keywords: TLM, thermal resistance, VCSEL, AlGaAs.

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1. Introduction

Vertical-cavity surface-emitting lasers (VCSELs) are a specific type of semiconductor laser, in that output radiation is emitted from their surface. This enables emission of a relatively low-divergent circular output beam for a semiconductor laser. As a result, VCSEL lasers are an attractive option for creating two-dimensional arrays. Currently, commercial applications of VCSELs are mainly limited to devices emitting red or near infrared radiation. They are used to provide light sources for optical data transmission, optical mice, detection systems, smartphones, thermal material processing systems, proximity sensors, distance measurement systems, face recognition, Light Detection and Ranging (Lidar), and 3D printers [1–5]. These applications require VCSELs with strictly defined operating parameters, necessitating careful design. Therefore, it is important to know the different design and material parameters relevant to the operation of VCSELs. Computer simulations can be very helpful, making it possible to study the impact of various material and design parameters on, for example, output power and threshold current. Numerical methods

are used to investigate many various interconnected physical phenomena occurring in VCSELs. They can also be used to separate and analyse a specific phenomenon, which is impossible with experimental methods. Moreover, using numerical methods can reduce the costs of manufacturing test structures. Unfortunately, not all of the values of material parameters necessary for numerical analysis have been measured precisely. Others may vary, depending on the fabricating system. Some, such as the resistance of electrical contacts, are mostly dependent on the technology used.

In this study, TLM measurements [9–11] were used to determine the electrical parameters of a VCSEL. The quality of the electrical contacts, especially the p-side contacts, has a significant impact on the performance of VCSELs. Equally important are the thermal properties of VCSELs because they influence the laser performance. In general, the thermal properties of a device are described in terms of thermal resistance. A low value for thermal resistance allows for more efficient operation. Therefore, thermal resistance was also measured, using a method similar to that described in [12]. A slightly different method of determining this parameter can be found in [13]. In future work, the electrical and thermal parameters determined here will be used in computer simulations of VCSELs.

2. Determination of lateral electrical conductivity

The VCSELs used in this study were produced by Vigo Photonics. The VCSELs were manufactured as GaAs/AlGaAs structures. Their top *distributed Bragg reflectors* (DBRs) are composed of 18 pairs of alternate layers of $\text{Al}_{0.9}\text{Ga}_{0.1}\text{As}$ and $\text{Al}_{0.2}\text{Ga}_{0.8}\text{As}$ of thicknesses approximately equal to a quarter of the emission wavelength each. The DBR layers are separated by thin gradient layers of compositions linearly changing from $\text{Al}_{0.9}\text{Ga}_{0.1}\text{As}$ to $\text{Al}_{0.2}\text{Ga}_{0.8}\text{As}$ or inversely. The VCSEL semiconductor structures are terminated on both sides by thin highly-doped GaAs layers, on which Ti/Pt/Au contacts are deposited. This structure is described in detail in [14].

Semiconductor samples with metallic contacts were submitted to *transmission line measurement* (TLM) (Fig. 1). This method was used to determine two electrical parameters important from the point of view of VCSEL operation:

- 1) surface resistivity of the metal–semiconductor contact,
- 2) lateral electrical conductivity of the semiconductor area below the contacts.

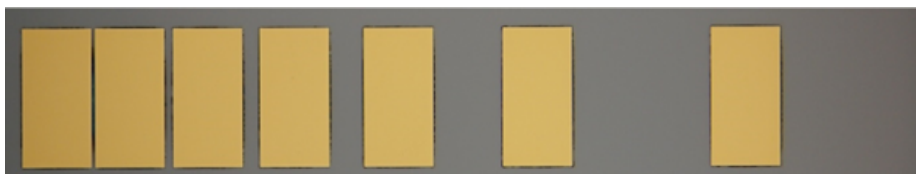


Fig. 1. Exemplary photographs of TLM samples produced by Vigo Photonics.

The TLM method consists in determining the resistance between adjacent contacts. In our measurement arrangement, the contacts were connected with the poles of a supply system by needles (Fig. 2 and Fig. 3). The current flowed from the first needle through the gold pad, then through the semiconductor area below, and finally reached the pad to which the second needle was connected (Fig. 2). Vertical current spreading was limited by the p–n junction, which presented a barrier to the current.

TLM measurements were carried out by the Photonics Group at Lodz University of Technology. During the measurements, current-voltage dependence was recorded, from which resistance

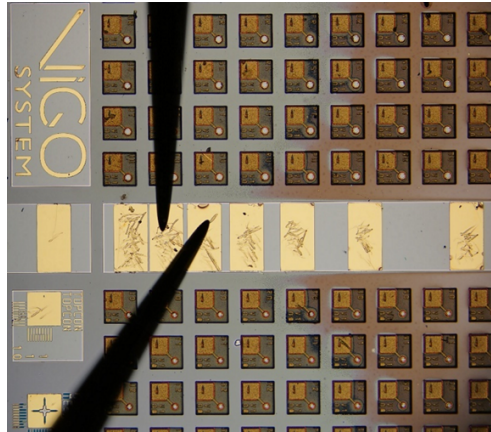
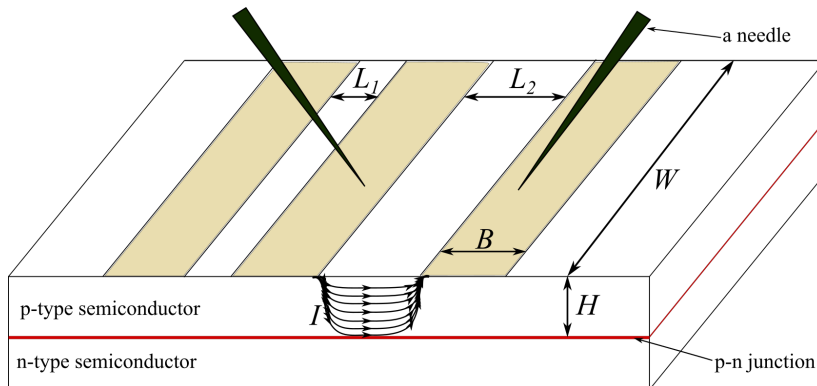


Fig. 2. Photograph of measured TLM samples produced by Vigo Photonics.


 Fig. 3. Scheme of the TLM measurement with current paths between the contacts indicated: L – distance between the contacts; W – width of the contacts; H – thickness of semiconductor layers conducting the current.

was determined. Device resistance is the sum of the contact resistances and the semiconductor resistance [15]. Measurements were carried out for various distances L between two contacts of the same width $W = 400 \mu\text{m}$ (Fig. 3). Distances L were between $10 \mu\text{m}$ and $3200 \mu\text{m}$. In general, the sample dimensions should meet the following dependence:

$$W \gg L \gg H, \quad (1)$$

where H is the thickness of the semiconductor layer below the contact. Dependence $R(L)$ is approximately linear and its slope coefficient α can be expressed as [16]:

$$\alpha = \frac{R_{\text{sh}}}{W} = \frac{1}{\sigma_p \cdot H \cdot W}, \quad (2)$$

where R_{sh} is the sheet resistance of the semiconductor layer below the contacts, σ_p is the effective electrical conductivity in the lateral direction of that layer, and H its thickness.

The condition $W \gg L$ in relation (1) is necessary to assume homogeneous current spreading for the whole width of the contact. Our sample does not satisfy this condition (see Fig. 2), but

a homogeneous current flow is still fulfilled as a result of etching the lateral areas to the depth below the p–n junction, which creates the mesa structure. In general, most VCSELs consist of alternately arranged thin layers of semiconductors, which form two DBRs located on either side of the junction. A detailed description of the analysed structures can be found in [Section 2.2](#).

The standard formulas used in the analysis of TLM measurements are derived with the following essential and generally not always true assumptions:

1. The thickness H of a layer conducting current is sufficiently low to assume a homogeneous current flow within the layer.
2. Electrical contacts are semi-infinite in the direction of current flow ($B = \infty$ – see Fig. 3).
3. Contact resistance is identical for both possible directions of the current flow through the metal-semiconductor contact.

The second assumption can be verified by determining the parameters with the aid of standard formulas. The current distribution along the direction of the current flow below the contact disappears exponentially as a function of the distance from the contact edge [16]. Hence, inaccuracy r following the second condition may be estimated as the ratio of the amount of current flowing through the real width of the contact (B) to the total current, both calculated using approximation (2). A simple integration gives:

$$r = \exp\left(-B\sqrt{\frac{\sigma_c}{H \cdot \sigma_p}}\right), \quad (3)$$

where H is thickness of the semiconductor area below the contacts, σ_p is the effective electrical conductivity of the semiconductor material, and σ_c is the electrical conductivity of the contacts. Parameter r in relation (3) describes the relative difference between the contact resistance of width B and a semi-infinite contact. Therefore, the contacts should be larger if the conductivity of the semiconductor material or its thickness increases, as well as when the conductivity of the contacts is worse. For the measurements presented in this paper, relation (3) leads to $r = 1.8 \cdot 10^{-11}$, which we consider to be a sufficiently low value.

It is impossible to verify the authenticity of the third assumption if the two contacts are identical, as they are in our case. Hence, we determine the average value for conductivity in two current-flow directions, up and down. When concentric annular contacts are used instead of perpendicular contacts, theoretical analysis becomes much more complex and analysis of measurement results is more difficult.

Figure 4 presents schemes of the structure with and without an etched mesa. The etching on the lateral areas enables measurements for larger ranges of the L parameter, which increases the accuracy with which the conductivity of the semiconductor layer can be determined, especially at higher values. Figure 5 presents resistance R of the area between adjacent contacts as a function

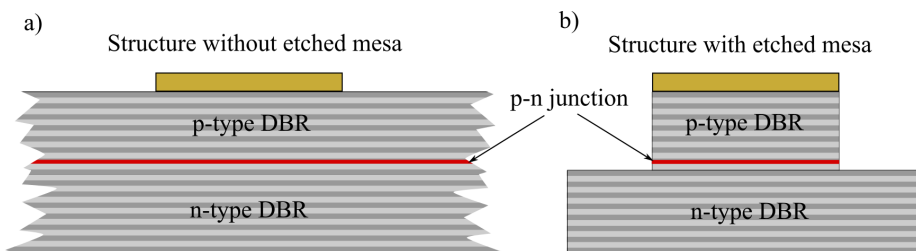


Fig. 4. Scheme of two types of structure submitted to TLM measurements: a) without an etched mesa, b) with an etched mesa.

of the distance between the contacts. It shows that mesa etching allows a linear $R(L)$ dependence to be obtained for significantly large values of the L parameter. This is especially important for measuring well-conducting semiconductors, for example, n-type semiconductors.

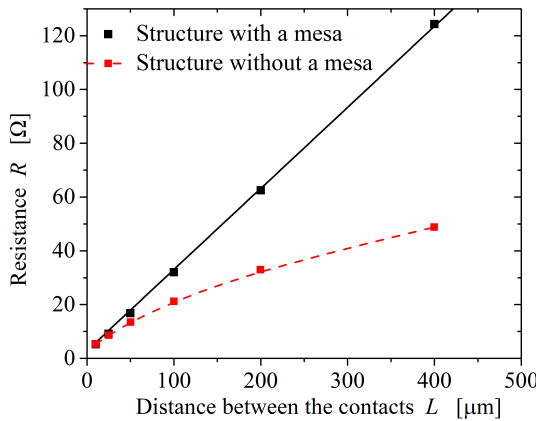


Fig. 5. Exemplary plots of the resistance R as a function of the distance between adjacent contacts for two structures: with a mesa and without a mesa.

Formula (2) was used to determine the conductivities of the semiconductor layers below the contacts at various heat-sink temperatures between 20°C and 80°C . The measurements were carried out for two contact structures, denoted here as TLM 1 and TLM 2. As an example, the current-voltage characteristic is presented in Fig. 6 for the TLM 1 sample at 20°C . The lateral electrical conductivity was about $3300/(\Omega\text{m})$ at 20°C and gradually fell as temperature increased to about $2800\text{--}2900/(\Omega\text{m})$ (Fig. 7). The calculations carried out for the TLM 1 sample show lower conductivities, because it was situated closer to an edge of the sample slab than the TLM 2 sample. The thickness of epitaxial layers (H parameter) is sometimes a little lower near to the sample edge than in the centre, which, following Formula (2), leads to lower calculated electrical conductivity.

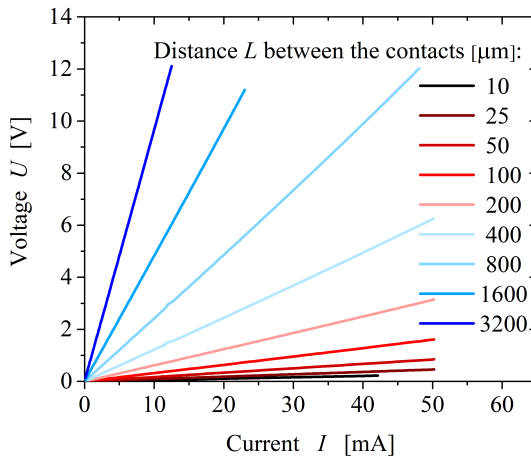


Fig. 6. Current-voltage characteristics at 20°C for the TLM 1 sample and for various distances L between the contacts.

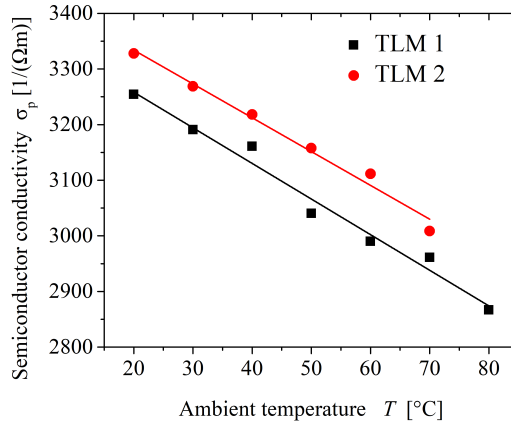


Fig. 7. Temperature dependence of the effective lateral electrical conductivity σ_p of the p-type semiconductor layers for two samples: TLM 1 and TLM 2.

The experimental values for contact resistance were in the range of $2 \cdot 10^{-5} \Omega\text{cm}^2$ – $1 \cdot 10^{-4} \Omega\text{cm}^2$ for temperatures between 20°C and 80°C . The average value of the slope coefficients of both the $\sigma_p(T)$ relations shown in Fig. 7 is $-6.24/(\Omega\text{mK})$. Contact conductivity was sufficiently high to assume that the resistance of the p-side contact was negligible compared to the device resistance. The cup layer (subcontact layer) on the p-side of the analysed laser was doped with Zn+ ions at the level of $1.2 \cdot 10^{20} \text{cm}^{-3}$. According to data from [17], the conductivity of p-type contacts doped with C+ ions of $1 \cdot 10^{20} \text{cm}^{-3}$ is $7 \cdot 10^{-6} \Omega\text{cm}^2$.

3. Determination of thermal resistance

In the second part of the study, we investigated the thermal resistance R_{th} of the VCSELs as a function of various heat-sink temperatures, based on measurements of its *light-current-voltage* (LIV) characteristics. Emission spectra were also recorded, using a Yokogawa AQ6370D Optical Spectrum Analyzer. Thermal resistance can be defined as a derivative of the laser temperature in the active area T_j over dissipated power P_{diss} :

$$R_{\text{th}} = \frac{dT_j}{dP_{\text{diss}}}, \quad (4)$$

where T_j is the temperature of the active-region and $P_{\text{diss}} = U \cdot I - P_{\text{out}}$, where P_{out} is the optical output power. The spectrum shift towards longer wavelengths (so called red shift) is caused by the increase of temperature in the active areas. The temperature of the laser can be raised by the flow of electric current through the laser or by the heating of its heat-sink. In the first case, changing the wavelength involves different mechanisms of power dissipation. On the other hand, the laser temperature depends on the power emitted by the device. Therefore, the following formula is correct:

$$\lambda(P_{\text{diss}}) = \lambda(T_j(P_{\text{diss}})). \quad (5)$$

After counting the derivative of relation (4), we obtain the following formula:

$$\frac{d\lambda}{dP_{\text{diss}}} = \frac{d\lambda}{dT_j} \cdot \frac{dT_j}{dP_{\text{diss}}}. \quad (6)$$

Using (4) and (6), the formula for thermal resistance can be presented using wavelength λ [5]:

$$R_{th} = \frac{dT_j}{d\lambda} \cdot \frac{d\lambda}{dP_{diss}}. \quad (7)$$

Two experiments were performed to determine the R_{th} . Each experiment was performed separately to determine the two components of the product of (7).

First, the laser spectra for the different temperatures of the heat sink T_{amb} were measured for a current value slightly above the threshold current to minimize the heating of the laser due to the current flow. Assuming a constant or low value for the current flowing through the laser, the wavelength shift is due to the change in the laser temperature caused by a change in the temperature of the heat-sink. Then, measuring the laser spectra enables determination of wavelengths corresponding to the highest emission peaks (Fig. 8), from which the slope $dT_{amb}/d\lambda$ of the $T_{amb}(\lambda)$ curve is determined. In our assumptions, this slope coefficient is equivalent to the $dT_j/d\lambda$. The measurements were carried out for constant temperatures of the heat-sink from 25°C to 85°C.

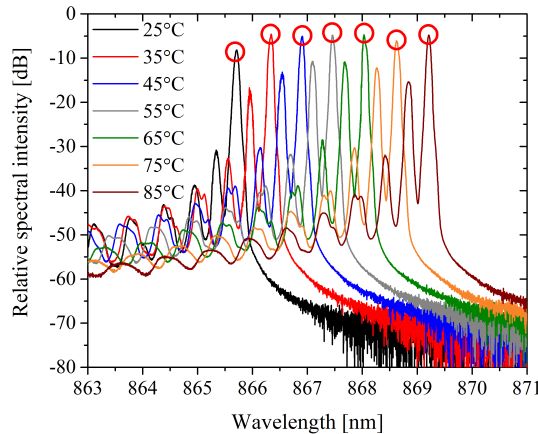


Fig. 8. VCSEL spectra determined for various heat-sink temperatures and currents slightly exceeding their lasing thresholds. The peaks corresponding to the longest wavelengths are marked by circles.

The second factor in (7), $d\lambda/dP_{diss}$, describes the changes in the laser’s wavelength caused by the increase in power dissipated in the device. It was determined from spectra measured at a constant temperature of the heat sink, but for different values of the driving current. Figure 9b presents the LIV characteristics at 25°C for three currents, 5 mA, 9 mA, and 12 mA. As can be seen, the main peak is shifted towards longer wavelengths as the current increases. Figure 10 shows the wavelength of the peak as a function of dissipated power $\lambda(P_{diss})$ for different temperatures of the heat-sink.

Dependence $\lambda(P_{diss})$ is approximately linear and enables determination of the $d\lambda/dP_{diss}$ value. As a consequence, the thermal resistance of the VCSEL can be determined using Formula (7). This procedure was applied for ambient temperatures T_{amb} within the range of 25–85°C, which showed the dependence of the thermal resistance on temperature $R_{th}(T)$ (Fig. 11).

For the investigated VCSEL at room temperature, the thermal resistance was equal to 1.87 K/mW. The thermal resistance depends on the electrical aperture of the laser and increases as the aperture size decreases. The analysed VCSEL has an electrical aperture of about 5 μm .

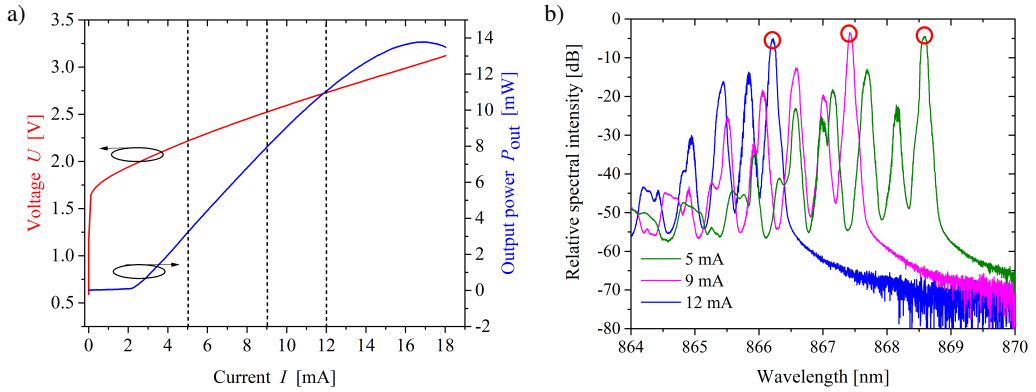


Fig. 9. Light-current-voltage (LIV) (a) and emission spectra (b) of the considered VCSEL at the ambient temperature of 25°C. Emission spectra (b) were recorded for three selected currents. Dashed lines in (a) indicate the currents for which red circles in (b) signify spectral peaks.

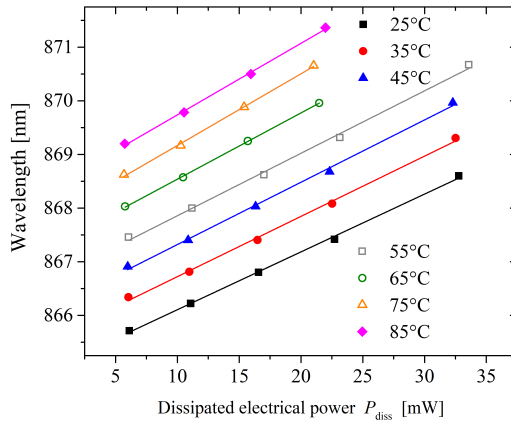


Fig. 10. Wavelength as a function of the dissipated power P_{diss} for the analysed VCSEL.

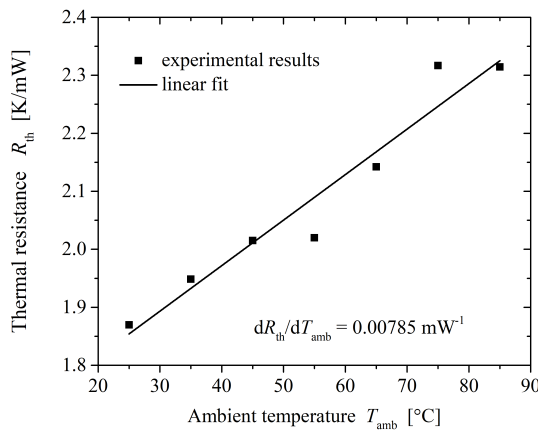


Fig. 11. Thermal resistance of the considered VCSEL as a function of temperature.

According to the literature data, VCSELs produced from arsenide material with similar apertures have thermal resistances in the range 0.5–2.8 K/mW [18–20]. Therefore, we can conclude that the analysed laser has good, relatively low thermal resistance.

4. Conclusions

In this study, a modified TLM method was used to characterize the parameters of VCSELs. We modified the standard TLM layout by etching a mesa which prevents the current from spreading outwards. This modification allowed us to use distances between the electrodes much bigger than their width which increases the accuracy of the measurement, especially when the conductivity of the semiconductor is high. The surface conductivity of the contacts and the conductivity of the semiconductor material were typical for p-type AlGaAs. The tested VCSELs were also found to have good thermal parameters, with low thermal resistance. The method described here enables measurements with larger distances between the VCSEL contacts, which improves their accuracy. This can be especially important in the samples where the semiconductor material has high conductivity. In future work, the determined electrical and thermal parameters will be used in computer simulations of VCSELs.

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